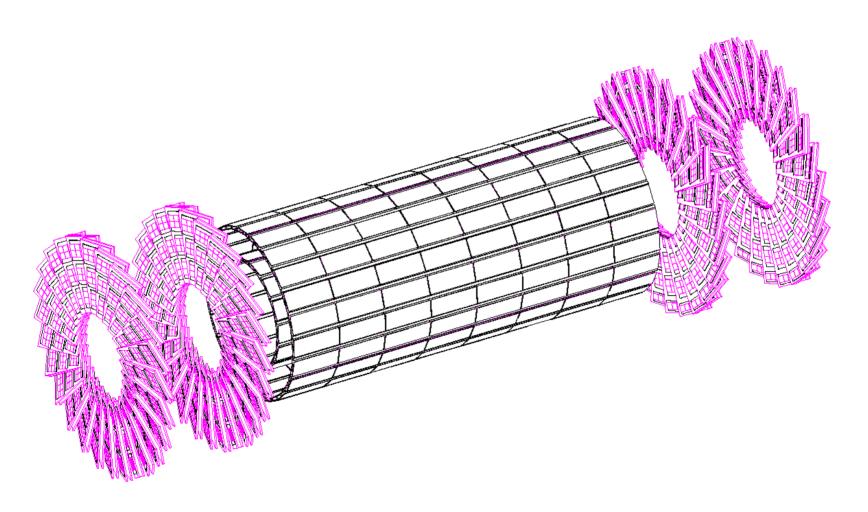
### Some Pixel Database Issues

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# **CMS Pixel Detector**



#### **Detector Dimensions**

#### **Barrels**

- Total 3 initally 2
- $z = \pm 266.6 \text{ mm}$
- r = 41.05 mm 104.26 mm

#### **Forward Disks**

- 4 Disks (current), 2 additional later
- $z = \pm 34.5$  cm,  $\pm 46.5$  cm
- $r_{min} = 6 cm$
- $r_{max} = 15 \text{ cm}$

**Total Coverage:**  $-2.52 < \eta < 2.52$ 

### What are we dealing with?

- Pixel size: 100 x 150 μm (0.25μm CMOS)
- Chip readout: 4160 pixels (52 cols x 80 rows)
- Total ROCs: 15,840 (3 barrels, 4 disks) 17,500 (3 barrels, 6 disks)
- Total Pixels ~ 66M (3 barrels, 4 disks)
   ~ 73M (3 barrels, 6 disks)

### **Pixel Databases**

- Construction Database
- Equipment Management Database
- Configuration Database
- Conditions Database

### **Construction Database**

- Track every component & history during production
- Aid in future troubleshooting
- Several institutions involved in fabrication
- Need secure access to database from remote location

### **Construction Database**

- Readout chip (example)
  - o wafer serial number bonded sensor
  - o test parameters
  - o module number
  - o Cable connected
  - o detector location
  - o DAC settings (?)
- Many components
  - o Sensors
  - o Readout chips
  - o Electronic components (VHDI, HDI, FEC, FED, TBM, etc)
  - o Cables
  - o Cooling
  - Support structures

### **Equipment Management Database**

- Construction Database will evolve into Equipment Management Database
- Keep track of the smallest replaceable unit in the detector
- Required by French INB to track all components exposed to radiation

- Stores entities necessary to start up a run
- Should be accessible to DAQ, DCS (controls), and the detector (for monitoring) systems
- Potential of being very large
- Information to bring each individual pixel and readout chip to operational state
- Information for other electronic components

Per Pixel Database entry (current estimate): 29 bytes

```
o Detector ID (barrel, B+ disks, or B- disks): 1 byte
o Module #: 4 bytes
o ROC ID: 4 bytes
o Pixel ID
    o double column #: 1 byte
    o row #: 1byte
o Thresholds (trim bits): 1 byte
o Mask bit: 1 byte
o Pedestals: 4 bytes
o Gain: 4 bytes
o Efficiencies: 4 bytes
Average rates: 4 bytes
```

- Storage for 1 calibration run (32 bytes/entry)
  - 2 GB (66M pixels)
  - o 2.4 GB (73M pixels)
- Per readout chip database entry (current estimate):
   40 bytes
  - o 28 DAC settings: 28 bytes (1 byte per DAC)
  - o 2 Control registers: 8 bytes (4 bytes per register)
  - o Temperature: 4 bytes
- Total per data collection
  - o 634 KB (4 disks)
  - o 700 KB (6 disks)

- Problem is not with storage size alone
- There is also the overhead incurred in
  - o Data retrieval from the database
  - o Data transfer
  - Data distribution to multiple locations (FEC, FED, monitor, etc.)
  - Data transfer to readout chips
- Other info
  - o Cooling monitor
  - o Hot pixel monitor
- Complex database. Implementation will not be easy

### **Conditions Database**

- Offline
- Calibration data
- Don't know much about it yet